

December 10, 1999

**Box Patent Application**

Assistant Commissioner for Patents  
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventors: Mike Chang, King Owyang, Yueh-Se Ho, Mohammed Kasem, Lixiong Luo, and Wei-Bing Chu

Title: Semiconductor Die Package Including Cup-Shaped Leadframe

X Return Receipt Postcard  
X This Transmittal Letter (in duplicate)  
4 page(s) Specification (not including claims)  
1 page(s) Claims (Figs. 1-7)  
1 page Abstract  
3 page(s) Declaration For Patent Application and Power of Attorney (Unsigned)  
1 Sheet(s) of Drawings

**CLAIMS AS FILED (fees computed under §1.9(f))**

For	Number Filed		Number Extra		Rate		Basic Fee
Total Claims	8	-20 =	0	x	\$18.00	=	\$ 760.00
Independent Claims	1	-3 =	0	x	\$78.00	=	\$ 0.00
<input type="checkbox"/>	Application contains one or more multiple dependent claims ( total fee)						\$
<input type="checkbox"/>	Fee for Request for Extension of Time						\$

Please make the following charges to Deposit Account 19-2386:

- ☒ Total fee for filing the patent application in the amount of \$ 760.00  
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL  
NO:

EL 375 515 878 US

Respectfully submitted,

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